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U.S. UTILITY Patent Application

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APPLICATION NO.	CONT/PRIOR	CLASS	SUBCLASS	ART UNIT	EXAMINER
09/941360	D	205	(A)	1741 40	Various -

Homayoun Talieh Cyprian Uzoh

Method and apparatus for plating and polishing a semiconductor substrate

ISSUING CLASSIFICATION					
ORIGINA	\L	CROSS REFERENCE(S)			
CLASS SUBCLASS	CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)			
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TERMINAL		DRAWINGS		CLAIMS ALLOWED		
DISCLAIMER	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.	
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not extend beyond the expiration date of U.S Patent. No.	·		ISSUE FEE			
				Amount Due	Date Paid	
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